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Product Change Notification - JAON-14YQYH505 (Printer Friendly)

Date: 19 Jul 2016
Product: Memory
Category:
Notification subject: CCB 2700 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L SOIC package at MMT assembly site
Notification text: **PCN Status:** Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CP.N.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L SOIC package at MMT assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site	MMT assembly site	MMT assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

September 2016

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

	July 2016				->	September 2016				
Workweek	27	28	29	30		35	36	37	38	39
			X							

Initial PCN Issue Date										
Qual Report Availability									X	
Final PCN Issue Date									X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

July 19, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-14YQYH505_Qual_Plan.pdf](#)
 - [PCN_JAON-14YQYH505_Affected_CPN.pdf](#)
 - [PCN_JAON-14YQYH505_Affected_CPN.xls](#)

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